

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L25	2	("6200389").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/14 20:45
S14	2	("20040083951").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/12 17:48
S15	3	("6730367").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/12 15:28
S16	11	((("4,260,649") or ("5,607,601") or ("5,659,383") or ("5,669,979") or ("5,814,156") or ("5,270,247") or ("5,023,424") or ("6,461,909") or ("6,503,330") or ("6,509,601") or ("6,448,192"))).PN.	USPAT	OR	OFF	2005/04/12 16:40
S17	14288	((118/58,620,665,666,692,712,713,715,722,724,725) or (156/345.25,345.26,345.27,345.29,345.33,345.50,345.51,345.52)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/12 17:52
S18	103	S17 and (dispens\$3 or dispers\$3 or distribut\$3) and (beam or electromagnetic or laser or (ultraviolet radiation)) and (reactive adj species)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/13 10:30
S19	2072	(dispens\$3 or dispers\$3 or distribut\$3) and (beam or electromagnetic or laser or (ultraviolet radiation)) and (reactive adj species)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/13 08:31
S20	658	S19 and (@ad>="20020305" or @rlad>="20020305")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/12 21:46

S21	565	S20 and (workpiece or (work piece) or substrate or wafer or (object adj2 treated))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/12 21:47
S22	544	S21 not S18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/12 19:25
S23	523	S22 and (etch\$3 or deposit\$4 or coat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/12 19:26
S24	394	S23 not dna	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/12 19:27
S25	1587	S17 and (dispens\$3 or dispers\$3 or distribut\$3) and (beam or electromagnetic or laser or (ultraviolet radiation))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/12 20:38
S26	177	S17 and (dispens\$3 or dispers\$3 or distribut\$3) and (beam or electromagnetic or laser or (ultraviolet radiation)) and ((exhaust or evacuation) port)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/12 21:13
S27	154	S26 not (S18 or S24)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/12 20:46
S28	20	S27 and (@ad>="20020305" or @rlad>="20020305")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/12 21:31

S29	245	S17 and (ald or ale or (atomic layer (deposition or epitax\$3)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/12 21:20
S31	128	S29 and (@ad<="20020305" or @rlad<="20020305")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/12 21:35
S32	1735	S19 and (@ad<="20020305" or @rlad<="20020305")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/13 11:28
S33	1412	S32 and (workpiece or (work piece) or substrate or wafer or (object adj2 treated))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/13 11:28
S34	911	S33 not (S31 or S27 or S24 or dna)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/13 11:29
S35	874	S34 and (etch\$3 or coat\$3 or deposit\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/12 21:59
S36	857	(Gurtej near3 Sandhu).in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/13 10:17
S37	4	(dispens\$3 or dispers\$3 or distribut\$3) same (first adj3 (nozzle or port or inlet)) same (second adj3 (nozzle or port or inlet)) same (third adj3 (nozzle or port or inlet)) same precursor same (inert or purge) same (reactive species)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/13 11:06

S38	5	((dispens\$3 or dispers\$3 or distribut\$3) same (first adj3 (nozzle or port or inlet)) same (second adj3 (nozzle or port or inlet)) same (third adj3 (nozzle or port or inlet))) and precursor and (inert or purge) and (reactive species))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/13 11:23
S39	1164	((dispens\$3 or dispers\$3 or distribut\$3) same (first adj3 (nozzle or port or inlet)) same (second adj3 (nozzle or port or inlet)) same (third adj3 (nozzle or port or inlet)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/13 11:23
S40	832	S39 and (@ad<="20020305" or @rlad<="20020305")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/13 11:28
S41	202	S40 and (workpiece or (work piece) or substrate or wafer or (object adj2 treated))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/13 11:28
S42	14288	((118/58,620,665,666,692,712,713,715,722,724,725) or (156/345.25,345.26,345.27,345.29,345.33,345.50,345.51,345.52)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/13 11:30
S43	103	S42 and (dispens\$3 or dispers\$3 or distribut\$3) and (beam or electromagnetic or laser or (ultraviolet radiation)) and (reactive adj species)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/13 11:30
S44	2072	(dispens\$3 or dispers\$3 or distribut\$3) and (beam or electromagnetic or laser or (ultraviolet radiation)) and (reactive adj species)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/13 11:30
S45	658	S44 and (@ad>="20020305" or @rlad>="20020305")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/13 11:30

S46	565	S45 and (workpiece or (work piece) or substrate or wafer or (object adj2 treated))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/13 11:30
S47	544	S46 not S43	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/13 11:30
S48	523	S47 and (etch\$3 or deposit\$4 or coat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/13 11:30
S49	394	S48 not dna	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/13 11:30
S50	177	S42 and (dispens\$3 or dispers\$3 or distribut\$3) and (beam or electromagnetic or laser or (ultraviolet radiation)) and ((exhaust or evacuation) port)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/13 11:30
S51	154	S50 not (S43 or S49)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/13 11:30
S52	245	S42 and (ald or ale or (atomic layer (deposition or epitax\$3)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/13 11:30
S53	128	S52 and (@ad<="20020305" or @rlad<="20020305")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/13 11:30

S54	1735	S44 and (@ad<="20020305" or @rlad<="20020305")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/13 11:30
S55	1412	S54 and (workpiece or (work piece) or substrate or wafer or (object adj2 treated))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/13 11:30
S56	911	S55 not (S53 or S51 or S49 or dna)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/13 11:30
S57	874	S56 and (etch\$3 or coat\$3 or deposit\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/13 11:30
S58	185	S41 not (S53 or S51 or S49 or dna or S57)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/04/13 11:31